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MAX77650/MAX77651

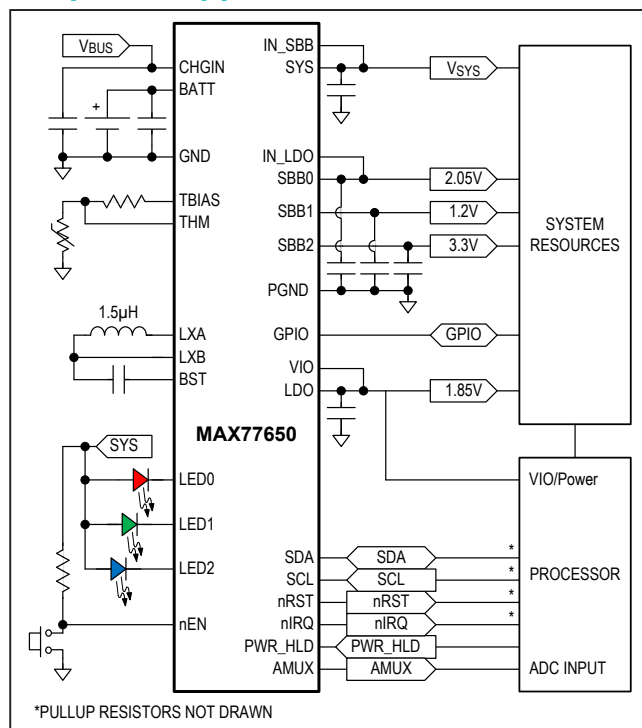
Ultra-Low Power PMIC with 3-Output SIMO and Power Path Charger for Small Li+

General Description

The MAX77650/MAX77651 provide highly-integrated battery charging and power supply solutions for low-power wearable applications where size and efficiency are critical. Both devices feature a SIMO buck-boost regulator that provides three independently programmable power rails from a single inductor to minimize total solution size. A 150mA LDO provides ripple rejection for audio and other noise-sensitive applications. A highly configurable linear charger supports a wide range of Li+ battery capacities and includes battery temperature monitoring for additional safety (JEITA).

The devices include other features such as current sinks for driving LED indicators and an analog multiplexer that switches several internal voltage and current signals to an external node for monitoring with an external ADC. A bidirectional I²C interface allows for configuring and checking the status of the devices. An internal on/off controller provides a controlled startup sequence for the regulators and provides supervisory functionality when the devices are on. Numerous factory programmable options allow the device to be tailored for many applications, enabling faster time to market.

Simplified Application Circuit



Benefits and Features

- Highly Integrated
 - Smart Power Selector™ Li+/Li-Poly Charger
 - 3 Output, Single-Inductor Multiple-Output (SIMO) Buck-Boost Regulator
 - 150mA LDO
 - 3-Channel Current Sink Driver
 - Analog MUX Output for Power Monitoring
- Low Power
 - 0.3µA Shutdown Current
 - 5.6µA Operating Current (3 SIMO Channels + LDO)
- Charger Optimized for Small Battery Size
 - Programmable Fast-Charge Current from 7.5mA to 300mA
 - Programmable Battery Regulation Voltage from 3.6V to 4.6V
 - Programmable Termination Current from 0.375mA to 45mA
 - JEITA Battery Temperature Monitors Adjust Charge Current and Battery Regulation Voltage for Safe Charging
- Flexible and Configurable
 - I²C Compatible Interface and GPIO
 - Factory OTP Options Available
- Small Size
 - 2.75mm x 2.15mm x 0.7mm WLP Package
 - 30-Bump, 0.4mm-Pitch WLP, 6x5 Array
 - Small Total Solution Size (19.2mm²)

Applications

- Bluetooth Headphones/Hearables
- Fitness, Health, and Activity Monitors
- Portable Devices
- Internet of Things (IoT)

Ordering Information appears at end of data sheet.

Smart Power Selector is a trademark of Maxim Integrated Products, Inc.

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Absolute Maximum Ratings

nEN, PWR_HLD, nIRQ, nRST to GND.....	-0.3V to V _{SYS} + 0.3V	IN_SBB to PGND.....	-0.3V to +6.0V
SCL, SDA, GPIO to GND.....	-0.3V to V _{IO} + 0.3V	LXA Continuous Current (Note 3).....	1.2A _{RMS}
CHGIN to GND.....	-0.3V to +30.0V	LXB Continuous Current (Note 4).....	1.2A _{RMS}
SYS, BATT to GND.....	-0.3V to +6.0V	SBB0, SBB1, SBB2 to PGND (Note 2).....	-0.3V to +6.0V
SYS to IN_SBB.....	-0.3V to +0.3V	BST to IN_SBB.....	-0.3V to +6.0V
V _L to GND.....	-0.3V to +6.0V	BST to LXB.....	-0.3V to +6.0V
AMUX, THM, TBIAS to GND.....	-0.3V to +6.0V	SBB0, SBB1, SBB2 Short-Circuit Duration.....	Continuous
nIRQ, nRST, SDA, AMUX, GPIO Continuous Current.....	±20mA	PGND to GND.....	-0.3V to +0.3V
CHGIN Continuous Current.....	1.2A _{RMS}	LGND to GND.....	-0.3V to +0.3V
SYS Continuous Current.....	1.2A _{RMS}	Operating Temperature Range.....	-40°C to +85°C
BATT Continuous Current (Note 1).....	1.2A _{RMS}	Junction Temperature.....	+150°C
LDO to GND (Note 2).....	-0.3V to V _{IN_LDO} + 0.3V	Storage Temperature Range.....	-65°C to +150°C
IN_LDO, V _{IO} to GND.....	-0.3V to the lower of (V _{SYS} + 0.3V) and +6.0V	Soldering Temperature (reflow).....	+260°C
LED0, LED1, LED2 to LGND.....	-0.3V to +6.0V	Continuous Power Dissipation (Multilayer Board) (T _A = +70°C, derate 20.4mW/°C above +70°C).....	1632mW

- Note 1:** Do not repeatedly hot-plug a source to the BATT terminal at a rate greater than 10Hz. Hot plugging low-impedance sources results in an ~8A momentary (~2µs) current spike.
- Note 2:** When the active discharge resistor is engaged, limit its power dissipation to an average of 10mW.
- Note 3:** LXA has internal clamping diodes to PGND and IN_SBB. It is normal for these diodes to briefly conduct during switching events. Avoid steady-state conduction of these diodes.
- Note 4:** Do not externally bias LXB. LXB has an internal low-side clamping diode to PGND, and an internal high-side clamping diode that dynamically shifts to the selected SIMO output. It is normal for these internal clamping diodes to briefly conduct during switching events. When the SIMO regulator is disabled, the LXB to PGND absolute maximum voltage is -0.3V to V_{SBB0} + 0.3V.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

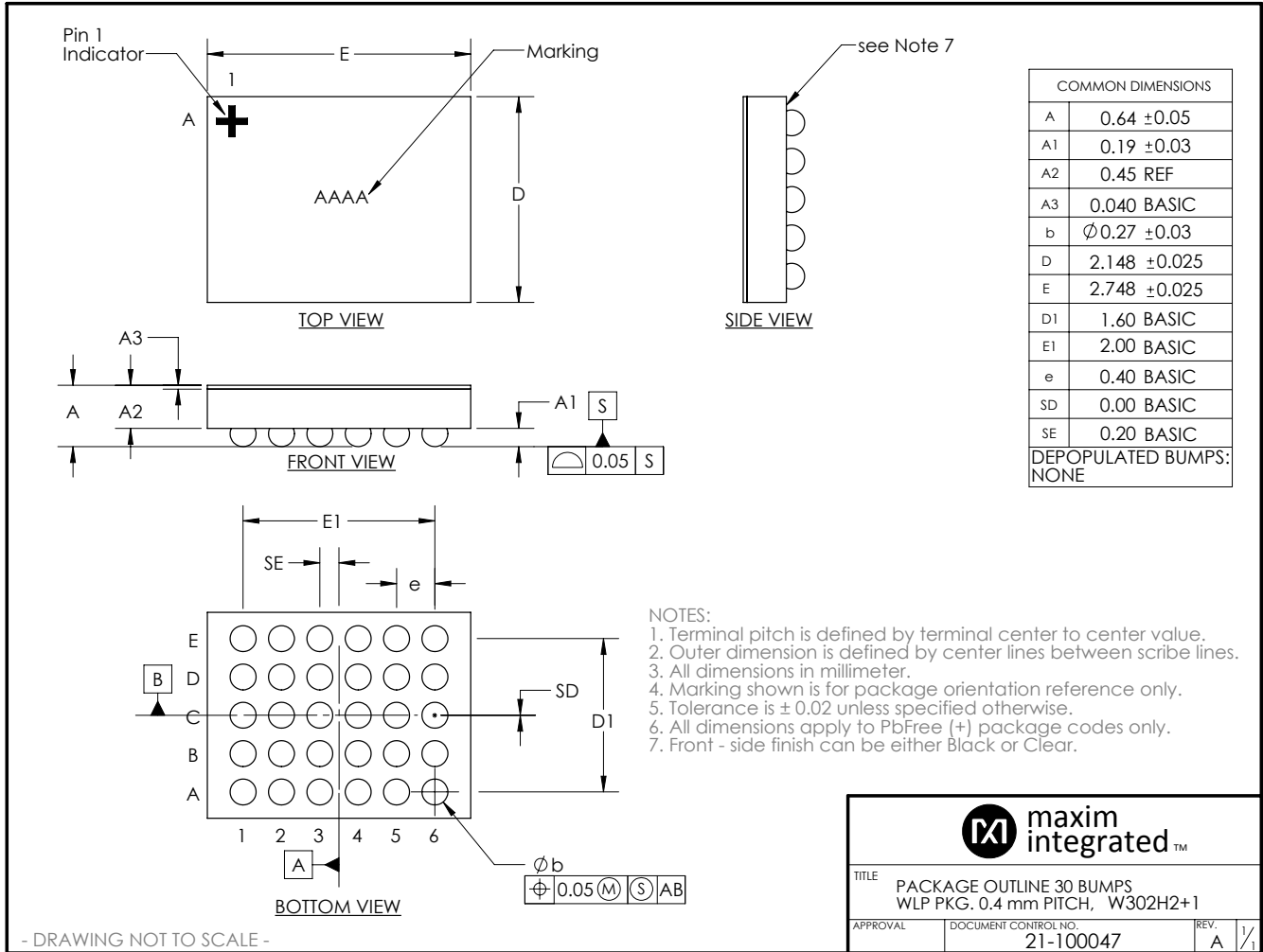
Package Information

PACKAGE CHARACTERISTICS	VALUES
Package Code	W302H2+1
Outline Number	21-100047
Land Pattern Number	Refer to Application Note 1891
Thermal Resistance, Four-Layer Board:	
Junction-to-Ambient (θ _{JA})	49°C/W (2s2p board)

For the latest package outline information and land patterns (footprints), go to www.maximintegrated.com/packages. Note that a "+", "#", or "-" in the package code indicates RoHS status only. Package drawings may show a different suffix character, but the drawing pertains to the package regardless of RoHS status.

Package thermal resistances were obtained using the method described in JEDEC specification JESD51-7, using a four-layer board. For detailed information on package thermal considerations, refer to www.maximintegrated.com/thermal-tutorial.

Package Information (continued)



Electrical Characteristics—Top Level

($V_{CHGIN} = 0V$, $V_{SYS} = V_{BATT} = V_{IN_SBB} = V_{IN_LDO} = 3.7V$, $V_{IO} = 1.8V$, limits are 100% production tested at $T_A = +25^\circ C$, limits over the operating temperature range ($T_A = -40^\circ C$ to $+85^\circ C$) are guaranteed by design and characterization, unless otherwise noted.)

PARAMETER	SYMBOL	CONDITIONS		MIN	TYP	MAX	UNITS
Operating Voltage Range	V_{SYS}			2.7		5.5	V
Shutdown Supply Current	I_{SHDN}	Current measured into BATT and SYS and IN_SBB and IN_LDO, all resources are off (LDO, SBB0, SBB1, SBB2, LED0, LED1, LED2), $T_A = 25^\circ C$	Main bias is off (SBIA_EN = 0). This is the standby state		0.3	1	μA
			Main bias is on in low-power mode (SBIA_EN = 1, SBIA_LPM = 1)		1		
			Main bias is on in normal-power mode (SBIA_EN = 1, SBIA_LPM = 0)		28		
Quiescent Supply Current	I_Q	Current measured into BATT and SYS and IN_SBB and IN_LDO. LDO, SBB0, SBB1, and SBB2 are enabled with no load. LED0, LED1, and LED2 are disabled	Main bias is in low-power mode (SBIA_LPM = 1)		5.6	13	μA
			Main bias is in normal-power mode (SBIA_LPM = 0)		40	60	

Electrical Characteristics—Global Resources

($V_{SYS} = 3.7V$, limits are 100% production tested at $T_A = +25^\circ C$, limits over the operating temperature range ($T_A = -40^\circ C$ to $+85^\circ C$) are guaranteed by design and characterization, unless otherwise noted.)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	
POWER-ON RESET (POR)							
POR Threshold	V_{POR}	V_{SYS} falling	1.6	1.9	2.1	V	
POR Threshold Hysteresis				100		mV	
UNDERVOLTAGE LOCKOUT (UVLO)							
UVLO Threshold	$V_{SYSUVLO}$	V_{SYS} falling, UVLO_F[3:0] = 0xA	2.5	2.6	2.7	V	
		V_{SYS} falling, UVLO_F[3:0] = 0xF	2.75	2.85	2.95		
UVLO Threshold Hysteresis	$V_{SYSUVLO_HYS}$	UVLO_H[3:0] = 0x5		300		mV	
OVERVOLTAGE LOCKOUT (OVLO)							
OVLO Threshold	$V_{SYSOVLO}$	V_{SYS} rising	5.70	5.85	6.00	V	
THERMAL MONITORS							
Overtemperature Lockout Threshold	T_{OTLO}	T_J rising		165		$^\circ C$	
Thermal Alarm Temperature 1	T_{JAL1}	T_J rising		80		$^\circ C$	
Thermal Alarm Temperature 2	T_{JAL2}	T_J rising		100		$^\circ C$	
Thermal Alarm Temperature Hysteresis				15		$^\circ C$	
ENABLE INPUT (nEN)							
nEN Input Leakage Current	I_{nEN_LKG}	$V_{SYS} = 5.5V$, $V_{nEN} = 0V$, and $5.5V$	$T_A = +25^\circ C$	-1	± 0.001	+1	μA
			$T_A = +85^\circ C$		± 0.01		

Electrical Characteristics—Global Resources (continued)

($V_{SYS} = 3.7V$, limits are 100% production tested at $T_A = +25^\circ C$, limits over the operating temperature range ($T_A = -40^\circ C$ to $+85^\circ C$) are guaranteed by design and characterization, unless otherwise noted.)

PARAMETER	SYMBOL	CONDITIONS		MIN	TYP	MAX	UNITS	
nEN Input Falling Threshold	$V_{TH_nEN_F}$	nEN falling		V_{SYS} - 1.4	V_{SYS} - 1.0		V	
nEN Input Rising Threshold	$V_{TH_nEN_F}$	nEN falling			V_{SYS} - 0.9	V_{SYS} - 0.6	V	
Debounce Time	t_{DBNC_nEN}	DBEN_nEN = 0			100		μs	
		DBEN_nEN = 1			30		ms	
Manual Reset Time	t_{MRST}	MRT_OTP = 0		14	16	20	s	
		MRT_OTP = 1		7	8	10.5		
POWER HOLD INPUT (PWR_HLD)								
PWR_HLD Input Leakage Current	$I_{PWR_HLD_LKG}$	$V_{SYS} = V_{IO} = 5.5V$, $V_{PWR_HLD} = 0V$, and 5.5V		$T_A = +25^\circ C$	-1	± 0.001	+1	μA
				$T_A = +85^\circ C$		± 0.01		
PWR_HLD Input Voltage Low	V_{IL}	$V_{IO} = 1.8V$				$0.3 \times V_{IO}$	V	
PWR_HLD Input Voltage High	V_{IH}	$V_{IO} = 1.8V$		$0.7 \times V_{IO}$			V	
PWR_HLD Input Hysteresis	V_{HYS}	$V_{IO} = 1.8V$			50		mV	
PWR_HLD Glitch Filter	$t_{PWR_HLD_GF}$	Both rising and falling edges are filtered			100		μs	
PWR_HLD Wait Time	$t_{PWR_HLD_WAIT}$	Maximum time for PWR_HLD input to assert after nRST deasserts during the power-up sequence		3.5	4.0	5.0	s	
OPEN-DRAIN INTERRUPT OUTPUT (nIRQ)								
Output Voltage Low	V_{OL}	$I_{SINK} = 2mA$				0.4	V	
Output Falling Edge Time	t_{f_nIRQ}	$C_{IRQ} = 25pF$			2		ns	
Leakage Current	I_{nIRQ_LKG}	$V_{SYS} = V_{IO} = 5.5V$, nIRQ set to be high impedance (i.e., no interrupts), $V_{nIRQ} = 0V$ and 5.5V		$T_A = +25^\circ C$	-1	± 0.001	+1	μA
				$T_A = +85^\circ C$		± 0.01		
OPEN-DRAIN RESET OUTPUT (nRST)								
Output Voltage Low	V_{OL}	$I_{SINK} = 2mA$				0.4	V	
Output Falling Edge Time	t_{f_nRST}	$C_{RST} = 25pF$			2		ns	
nRST Deassert Delay Time	t_{RSTODD}	See Figure 5 and Figure 7 for more information			5.12		ms	
nRST Assert Delay Time	t_{RSTOAD}	See Figure 5 for more information			10.24		ms	
Leakage Current	I_{nRST_LKG}	$V_{SYS} = V_{IO} = 5.5V$, nRST set to be high impedance (i.e., not reset), $V_{nRST} = 0V$ and 5.5V		$T_A = +25^\circ C$	-1	± 0.001	+1	μA
				$T_A = +85^\circ C$		± 0.01		

Electrical Characteristics—Global Resources (continued)

($V_{SYS} = 3.7V$, limits are 100% production tested at $T_A = +25^\circ C$, limits over the operating temperature range ($T_A = -40^\circ C$ to $+85^\circ C$) are guaranteed by design and characterization, unless otherwise noted.)

PARAMETER	SYMBOL	CONDITIONS		MIN	TYP	MAX	UNITS
GENERAL-PURPOSE INPUT/OUTPUT (GPIO)							
Input Voltage Low	V_{IL}	$V_{IO} = 1.8V$				$0.3 \times V_{IO}$	V
Input Voltage High	V_{IH}	$V_{IO} = 1.8V$		$0.7 \times V_{IO}$			V
Input Leakage Current	I_{GPI_LKG}	DIR = 1, $V_{IO} = 5.5V$, $V_{GPIO} = 0V$ and 5.5V	$T_A = +25^\circ C$	-1	± 0.001	+1	μA
			$T_A = +85^\circ C$			± 0.01	
Output Voltage Low	V_{OL}	$I_{SINK} = 2mA$				0.4	V
Output Voltage High	V_{OH}	$I_{SOURCE} = 1mA$		$0.8 \times V_{IO}$			V
Input Debounce Time	t_{DBNC_GPI}	DBEN_GPI = 1			30		ms
Output Falling Edge Time	t_f_GPIO	$C_{GPIO} = 25pF$			3		ns
Output Rising Edge Time	t_r_GPIO	$C_{GPIO} = 25pF$			3		ns
FLEXIBLE POWER SEQUENCER							
Power-Up Event Periods	t_{EN}	See Figure 6			1.28		ms
Power-Down Event Periods	t_{DIS}	See Figure 6			2.56		ms

Electrical Characteristics—Smart Power Selector Charger

($V_{CHGIN} = 5.0V$, $V_{SYS} = 4.5V$, $V_{BATT} = 4.2V$, limits are 100% production tested at $T_A = +25^\circ C$, limits over the operating temperature range ($T_A = -40^\circ C$ to $+85^\circ C$) are guaranteed by design and characterization, unless otherwise noted.)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
DC INPUT						
CHGIN Valid Voltage Range	V_{CHGIN}	Initial CHGIN voltage before enabling charging	4.10		7.25	V
CHGIN Standoff Voltage Range	$V_{STANDOFF}$	DC rising		28		V
CHGIN Overvoltage Threshold	V_{CHGIN_OVP}	DC rising	7.25	7.50	7.75	V
CHGIN Overvoltage Hysteresis				100		mV
CHGIN Undervoltage Lockout	V_{CHGIN_UVLO}	DC rising	3.9	4.0	4.1	V
CHGIN Undervoltage Lockout Hysteresis				500		mV
Input Current Limit Range	I_{CHGIN_LIM}	$V_{SYS} = V_{SYS_REG} - 100mV$, programmable in 95mA steps	95		475	mA

Electrical Characteristics—Smart Power Selector Charger (continued)

($V_{CHGIN} = 5.0V$, $V_{SYS} = 4.5V$, $V_{BATT} = 4.2V$, limits are 100% production tested at $T_A = +25^\circ C$, limits over the operating temperature range ($T_A = -40^\circ C$ to $+85^\circ C$) are guaranteed by design and characterization, unless otherwise noted.)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Input Current Limit Accuracy		$I_{CHGIN-LIM} = 95mA$, $V_{SYS} = V_{SYS-REG} - 100mV$	90	95	100	mA
Minimum Input Voltage Regulation Range	$V_{CHGIN-MIN}$	V_{CHGIN} falling due to loading conditions and/or high-impedance charge source, programmable in 100mV increments with $V_{CHGIN_MIN}[2:0]$.	4.0		4.7	V
Minimum Input Voltage Regulation Accuracy		$V_{CHGIN-MIN} = 4.5V$ ($V_{CHGIN_MIN}[2:0] = 0b101$), I_{CHGIN} reduced by 10%	4.32	4.50	4.68	V
Charger Input Debounce Timer	$t_{CHGIN-DB}$	$V_{CHGIN} = 5V$, time before CHGIN is allowed to deliver current to SYS or BATT	100	120	140	ms
SUPPLY AND QUIESCENT CURRENTS						
BATT Bias Current	$I_{BATT-BIAS}$	$V_{CHGIN} = 5V$, charger is not in USB suspend ($USBS = 0$), charging is finished (CHG_DTLS indicate done), $I_{SYS} = 0mA$		5		μA
CHGIN Supply Current	I_{CHGIN}	$V_{CHGIN} = 5V$, charger is not in USB suspend ($USBS = 0$), Charging is finished (CHG_DTLS indicate done), $I_{SYS} = 0mA$		1.0	1.8	mA
		$V_{CHGIN} = 0V$ to 1V, $V_{BATT} = 3.3V$, $I_{SYS} = 0A$			50	μA
CHGIN Suspend Supply Current	I_{CHGIN}	$V_{CHGIN} = 5V$, charger in USB suspend ($USBS = 1$)			50	μA
PREQUALIFICATIONS						
Charge Current Soft-Start Slew Time		Zero to full scale		1		ms
Input Current Soft-Start Slew Time		Zero to full scale		1		ms
Prequalification Voltage Threshold Range	V_{PQ}	Charger is in prequalification mode when $V_{BATT} < V_{PQ}$, this threshold has 100mV of hysteresis, programmable in 100mV steps with $CHG_PQ[2:0]$	2.3		3.0	V
Prequalification Voltage Threshold Accuracy		$V_{PQ} = 3.0V$	-3		+3	%
Prequalification Mode Charge Current	I_{PQ}	$V_{BATT} = 2.5V$, $V_{PQ} = 3.0V$, expressed as a percentage of $I_{FAST-CHG}$, $I_{PQ} = 0$		10		%
		$V_{BATT} = 2.5V$, $V_{PQ} = 3.0V$, expressed as a percentage of $I_{FAST-CHG}$, $I_{PQ} = 1$		20		
Prequalification Safety Timer	t_{PQ}	$V_{BATT} < V_{PQ} = 3.0V$	27	30	33	minutes

Electrical Characteristics—Smart Power Selector Charger (continued)

($V_{CHGIN} = 5.0V$, $V_{SYS} = 4.5V$, $V_{BATT} = 4.2V$, limits are 100% production tested at $T_A = +25^\circ C$, limits over the operating temperature range ($T_A = -40^\circ C$ to $+85^\circ C$) are guaranteed by design and characterization, unless otherwise noted.)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
FAST CHARGE						
Fast-Charge Voltage Range	$V_{FAST-CHG}$	$I_{BATT} = 0mA$, programmable in 25mV steps with CHG_CV[5:0]	3.6		4.6	V
Fast-Charge Voltage Accuracy		$I_{BATT} = 0mA$, $V_{FAST-CHG} = 4.3V$, $V_{SYS} = 4.5V$, $T_A = +25^\circ C$	-0.5	± 0.15	+0.5	%
		$I_{BATT} = 0mA$, $V_{FAST-CHG} = 3.6V$ to $4.6V$, $V_{SYS} = 4.8V$			1.0	
Fast-Charge Current Range	$I_{FAST-CHG}$	Programmable in 7.5mA steps with CHG_CC[5:0]	7.5		300	mA
Fast-Charge Current Accuracy		$I_{FAST-CHG} = 15mA$, $T_A = 25^\circ C$, $V_{BATT} = V_{FAST-CHG} - 300mV$	-1.5		+1.5	%
		$I_{FAST-CHG} = 300mA$, $T_A = 25^\circ C$, $V_{BATT} = V_{FAST-CHG} - 300mV$	-1.5		+1.5	
Fast-Charge Current Accuracy over Temperature		Across all current settings, $V_{BATT} = V_{FAST-CHG} - 300mV$	-10		+10	%
Fast-Charge Safety Timer Range	t_{FC}	Programmable in 2 hour increments or disabled with T_FAST_CHG[1:0], from prequal done to timer fault	3		7	hours
Fast-Charge Safety Timer Accuracy		$t_{FC} = 3$ hours	-10		+10	%
Fast-Charge Safety Timer Suspend Threshold		Fast-charge CC mode, loading conditions and/or a weak charging source caused charge current to drop below this threshold, expressed as a percentage of $I_{FAST-CHG}$		20		%
Junction Temperature Regulation Setting Range	T_{J-REG}	Programmable in $10^\circ C$ steps with TJ_REG[2:0]	60		100	$^\circ C$
Junction Temperature Regulation Loop Gain	G_{TJ-REG}	Rate at which $I_{FAST-CHG}/I_{PQ}$ is reduced to maintain T_{J-REG} , expressed a percentage of $I_{FAST-CHG}/I_{PQ}$ per degree centigrade rise		-5.4		%/ $^\circ C$
TERMINATION AND TOPOFF						
End-of-Charge Termination Current	I_{TERM}	$I_{TERM} = 0b00$ (expressed as a percentage of $I_{FAST-CHG}$)		5		%
		$I_{TERM} = 0b01$ (expressed as a percentage of $I_{FAST-CHG}$)		7.5		
		$I_{TERM} = 0b10$ (expressed as a percentage of $I_{FAST-CHG}$)		10		
		$I_{TERM} = 0b11$ (expressed as a percentage of $I_{FAST-CHG}$)		15		

Electrical Characteristics—Smart Power Selector Charger (continued)

($V_{CHGIN} = 5.0V$, $V_{SYS} = 4.5V$, $V_{BATT} = 4.2V$, limits are 100% production tested at $T_A = +25^\circ C$, limits over the operating temperature range ($T_A = -40^\circ C$ to $+85^\circ C$) are guaranteed by design and characterization, unless otherwise noted.)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
End-of-Charge Termination Current Accuracy		$I_{FAST-CHG} = 15mA$, $I_{TERM} = 1.5mA$ (10% of $I_{FAST-CHG}$), $T_A = +25^\circ C$	1.35	1.5	1.65	mA
		$I_{FAST-CHG} = 300mA$, $I_{TERM} = 30mA$ (10% of $I_{FAST-CHG}$), $T_A = +25^\circ C$	27	30	33	
Top-Off Timer Range	t_{TO}	$I_{BATT} < I_{TERM}$, programmable in 5 minute steps with $T_TOPOFF[2:0]$	0		35	minutes
Top-Off Timer Accuracy		$t_{TO} = 10$ minutes	-10		+10	%
Charge Restart Threshold	$V_{RESTART}$	$CHG = 0$ (charging done), charging resumes when $V_{BATT} < V_{FAST-CHG} - V_{RESTART}$	65	150		mV
DEVICE ON-RESISTANCE AND LEAKAGE						
BATT to SYS On-Resistance		$V_{BATT} = 3.7V$, $I_{BATT} = 300mA$, $V_{CHGIN} = 0V$, battery is discharging to SYS		100		$m\Omega$
Charger FET Leakage Current		$V_{SYS} = 4.5V$, $V_{BATT} = 0V$, $T_A = 25^\circ C$, charger disabled		0.1	1.0	μA
		$V_{SYS} = 4.5V$, $V_{BATT} = 0V$, $T_A = 85^\circ C$, charger disabled		1		
CHGIN to SYS On-Resistance		$V_{CHGIN} = 4.65V$		600		$m\Omega$
Input FET Leakage Current		$V_{CHGIN} = 0V$, $V_{SYS} = 4.2V$, $T_A = +25^\circ C$, body-switched diode reverse biased		0.1	1.0	μA
		$V_{CHGIN} = 0V$, $V_{SYS} = 4.2V$, $T_A = +85^\circ C$, body-switched diode is reverse biased		1		
SYSTEM NODE						
System Voltage Regulation Range	$V_{SYS-REG}$	Programmable in 25mV steps with $V_{SYS_REG}[4:0]$	4.1		4.8	V
System Voltage Regulation Accuracy	V_{SYS}	$V_{SYS-REG} = 4.5V$, $I_{SYS} = 1mA$, $T_A = +25^\circ C$	4.41	4.50	4.59	V
		$V_{SYS-REG} = 4.5V$, $I_{SYS} = 1mA$, $T_A = -40^\circ C$ to $+85^\circ C$	4.365	4.500	4.635	
Minimum System Voltage Regulation Loop Setpoint	$V_{SYS-MIN}$	$V_{CHGIN} = 5V$, $V_{SYS-REG} = 4.5V$, $V_{SYS} < V_{SYS-REG}$ due to $I_{CHGIN} = I_{CHGIN-LIM}$ (input in current-limit), battery charging, I_{BATT} reduced to 50% of $I_{FAST-CHG}$ (minimum system voltage regulation active)	4.34	4.4	4.45	V
Supplement Mode System Voltage Regulation		$I_{SYS} = 150mA$		$V_{BATT} - 0.15V$		V

Electrical Characteristics—Adjustable Thermistor Temperature Monitors

($V_{CHGIN} = 5.0V$, $V_{SYS} = 4.5V$, $V_{BATT} = 4.2V$, limits are 100% production tested at $T_A = +25^\circ C$, limits over the operating temperature range ($T_A = -40^\circ C$ to $+85^\circ C$) are guaranteed by design and characterization, unless otherwise noted.)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
JEITA TEMPERATURE MONITORS						
TBIAS Voltage	V_{TBIAS}	THM_EN = 1, $V_{CHGIN} = 5V$		1.25		V
JEITA Cold Threshold Range	V_{COLD}	Voltage rising threshold, programmable with THM_COLD[1:0] in $5^\circ C$ increments when using an NTC $\beta = 3380K$	0.867		1.024	V
JEITA Cool Threshold Range	V_{COOL}	Voltage rising threshold, programmable with THM_COOL[1:0] in $5^\circ C$ increments when using an NTC $\beta = 3380K$	0.747		0.923	V
JEITA Warm Threshold Range	V_{WARM}	Voltage falling threshold, programmable with THM_WARM[1:0] in $5^\circ C$ increments when using an NTC $\beta = 3380K$	0.367		0.511	V
JEITA Hot Threshold Range	V_{HOT}	Voltage falling threshold, programmable with THM_HOT[1:0] in $5^\circ C$ increments when using an NTC $\beta = 3380K$	0.291		0.411	V
Temperature Threshold Accuracy		Voltage threshold accuracy expressed as temperature for an NTC $\beta = 3380K$		± 3		$^\circ C$
Temperature Threshold Hysteresis		Temperature hysteresis set on each voltage threshold for an NTC $\beta = 3380K$		3		$^\circ C$
JEITA Modified Fast-Charge Voltage Range	$V_{FAST-CHG_JEITA}$	$I_{BATT} = 0mA$, programmable in 25mV steps, battery is either cool or warm	3.6		4.6	V
JEITA Modified Fast-Charge Current Range	$I_{FAST-CHG_JEITA}$	Programmable in 7.5mA steps, battery is either cool or warm	7.5		300	mA

Electrical Characteristics—Analog Multiplexer and Power Monitor AFEs

($V_{CHGIN} = 5.0V$, $V_{SYS} = 4.5V$, $V_{BATT} = 4.2V$, limits are 100% production tested at $T_A = +25^\circ C$, limits over the operating temperature range ($T_A = -40^\circ C$ to $+85^\circ C$) are guaranteed by design and characterization, unless otherwise noted.)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
ANALOG MULTIPLEXER AND POWER MONITOR AFEs						
Full-Scale Voltage	V_{FS}			1.25		V
SYS Voltage Monitor Gain	$G_{V_{SYS}}$	V_{FS} corresponds to maximum $V_{SYS-REG}$ setting		0.26		V/V
CHGIN POWER						
CHGIN Current Monitor Gain	$G_{I_{CHGIN}}$	V_{FS} corresponds to maximum $I_{CHGIN-LIM}$ setting		2.632		V/A
CHGIN Voltage Monitor Gain	$G_{V_{CHGIN}}$	V_{FS} corresponds to V_{CHGIN_OVP}		0.167		V/V
BATT MONITOR						
Battery Charge Current Monitor Gain	$G_{I_{BATT-CHG}}$	V_{FS} corresponds to 100% of $I_{FAST-CHG}$ setting (CHG_CC[5:0])		12.5		mV/%

Electrical Characteristics—Analog Multiplexer and Power Monitor AFEs (continued)

($V_{CHGIN} = 5.0V$, $V_{SYS} = 4.5V$, $V_{BATT} = 4.2V$, limits are 100% production tested at $T_A = +25^\circ C$, limits over the operating temperature range ($T_A = -40^\circ C$ to $+85^\circ C$) are guaranteed by design and characterization, unless otherwise noted.)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Charge Current Monitor Accuracy		$I_{FAST-CHG} = 15mA$, $T_A = 25^\circ C$, $V_{BATT} = V_{FAST-CHG} - 300mV$	-3.5		+3.5	%
		$I_{FAST-CHG} = 300mA$, $T_A = +25^\circ C$, $V_{BATT} = V_{FAST-CHG} - 300mV$	-3.5		+3.5	
Charge Current Monitor Accuracy over Temperature		Across all current settings, $V_{BATT} = V_{FAST-CHG} - 300mV$	-10		+10	%
Battery Discharge Monitor Full-Scale Current Range	$I_{DISCHG-SCALE}$	Programmable with IMON_DISCHG_SCALE[3:0]	8.2		300	mA
Battery Discharge Current Monitor Accuracy		15mA to 300mA battery discharge current, $I_{DISCHG-SCALE} = 300mA$	-15		+15	%
Battery Discharge Current Monitor Offset		$I_{BATT} = 0mA$	-0.5		+0.65	mA
Battery Voltage Monitor Gain	G_{VBATT}	V_{FS} corresponds to maximum $V_{FAST-CHG}$ setting		0.272		V/V
ANALOG MULTIPLEXER						
Channel Switching Time				0.3		μs
Off Leakage Current		$V_{AMUX} = 0V$, AMUX is high impedance	$T_A = +25^\circ C$	1	500	nA
			$T_A = +85^\circ C$	1		μA
THM AND TBIAS						
THM Voltage Monitor Gain	G_{VTHM}			1		V/V
TBIAS Voltage Monitor Gain	G_{VTBIAS}			1		V/V

Electrical Characteristics—SIMO Buck-Boost

($V_{SYS} = 3.7V$, $V_{IN_SBB} = 3.7V$, $C_{SBBx} = 10\mu F$, $L = 1.5\mu H$, limits are 100% production tested at $T_A = +25^\circ C$, limits over the operating temperature range ($T_A = -40^\circ C$ to $+85^\circ C$) are guaranteed by design and characterization, unless otherwise noted.)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
OUTPUT VOLTAGE RANGE (SBB0)						
Minimum Output Voltage				0.8		V
Maximum Output Voltage				2.375		V
Output DAC Bits				6		bits
Output DAC LSB Size				25		mV
OUTPUT VOLTAGE RANGE (SBB1)						
Minimum Output Voltage		MAX77650		0.8		V
		MAX77651		2.4		
Maximum Output Voltage		MAX77650		1.5875		V
		MAX77651		5.25		
Output DAC Bits				6		bits
Output DAC LSB Size		MAX77650		12.5		mV
		MAX77651		50		
OUTPUT VOLTAGE RANGE (SBB2)						
Minimum Output Voltage		MAX77650		0.8		V
		MAX77651		2.4		
Maximum Output Voltage		MAX77650		3.95		V
		MAX77651		5.25		
Output DAC Bits				6		bits
Output DAC LSB Size				50		mV
OUTPUT VOLTAGE ACCURACY						
Output Voltage Accuracy		V_{SBBx} falling, threshold where LXA switches high. Specified as a percentage of target output voltage (Note 3)	$T_A = +25^\circ C$	-2.5	+2.5	%
			$T_A = -40^\circ C$ to $+85^\circ C$	-4.0	+4.0	
TIMING CHARACTERISTICS						
Enable Delay		Delay time from the SIMO receiving its first enable signal to when it begins to switch in order to service that output.		60		μs
Soft-Start Slew Rate	dV/dt_{SS}		3.3	5.0	6.6	$mV/\mu s$

Electrical Characteristics—SIMO Buck-Boost (continued)

($V_{SYS} = 3.7V$, $V_{IN_SBB} = 3.7V$, $C_{SBBx} = 10\mu F$, $L = 1.5\mu H$, limits are 100% production tested at $T_A = +25^\circ C$, limits over the operating temperature range ($T_A = -40^\circ C$ to $+85^\circ C$) are guaranteed by design and characterization, unless otherwise noted.)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	
POWER STAGE CHARACTERISTICS							
LXA Leakage Current		SBB0, SBB1, SBB2 are disabled, $V_{IN_SBB} = 5.5V$, $V_{LXA} = 0V$, or $5.5V$	$T_A = +25^\circ C$	-1.0	± 0.1	+1.0	μA
			$T_A = +85^\circ C$		± 1.0		
LXB Leakage Current		SBB0, SBB1, SBB2 are disabled, $V_{IN_SBB} = 5.5V$, $V_{LXA} = 0V$ or $5.5V$, all $V_{SBBx} = 5.5V$	$T_A = +25^\circ C$	-1.0	± 0.1	+1.0	μA
			$T_A = +85^\circ C$		± 1.0		
BST Leakage Current		$V_{IN_SBB} = 5.5V$, $V_{LXB} = 5.5V$, $V_{BST} = 11V$	$T_A = +25^\circ C$		+0.01	+1.0	μA
			$T_A = +85^\circ C$		+0.1		
Disabled Output Leakage Current		SBB0, SBB1, SBB2 are disabled, active-discharge disabled ($ADE_SBBx = 0$), $V_{SBBx} = 5.5V$, $V_{LXB} = 0V$, $V_{SYS} = V_{IN_SBB} = V_{BST} = 5.5V$	$T_A = +25^\circ C$		+0.1	+1.0	μA
			$T_A = +85^\circ C$		+0.2		
Active Discharge Impedance	R_{AD_SBBx}	SBB0, SBB1, SBB2 are disabled, active discharge enabled ($ADE_SBBx = 1$)	80	140	260	Ω	
CONTROL SCHEME							
Peak Current Limit (Note 4)	I_{P_SBB}	$IP_SBBx = 0b11$	0.414	0.500	0.586	A	
		$IP_SBBx = 0b10$	0.589	0.707	0.806		
		$IP_SBBx = 0b01$	0.713	0.866	0.947		
		$IP_SBBx = 0b00$	0.892	1.000	1.108		

Note 3: Measured in an open-loop test that determines the output voltage falling threshold where LXA switches high.

Note 4: Typical values align with bench observations using the stated conditions. Minimum and maximum values are tested in production with DC currents. See the [Typical Operating Characteristics](#) SIMO switching waveforms to gain more insight on this specification.

Electrical Characteristics—LDO

($V_{SYS} = 3.7V$, $V_{IN_LDO} = 2.05V$, $V_{LDO} = 1.85V$, $C_{LDO} = 10\mu F$, limits are 100% production tested at $T_A = +25^\circ C$, limits over the operating temperature range ($T_A = -40^\circ C$ to $+85^\circ C$) are guaranteed by design and characterization, unless otherwise noted.)

PARAMETER	SYMBOL	CONDITIONS		MIN	TYP	MAX	UNITS
GENERAL CHARACTERISTICS							
Input Voltage	V_{IN_LDO}	IN_LDO cannot exceed SYS voltage (Note 5)		1.8		5.5	V
LDO Shutdown Current	I_{IN_LDO}	Current measured into IN_LDO, LDO output disabled (Note 6)			0.1	1	μA
LDO Quiescent Supply Current (Note 6)	I_{IN_LDO}	Current measured into IN_LDO, $I_{LDO} = 0mA$	LDO output enabled and in regulation, $V_{IN_LDO} = 2.05V$, $V_{LDO} = 1.85V$		1.7	5.15	μA
			LDO output enabled and in dropout, $V_{IN_LDO} = 1.8V$, V_{LDO} target is 1.85V		2.3		
Maximum Output Current	I_{OUT}			150			mA
Current Limit		V_{LDO} externally forced to 1.3V		165	255	375	mA
OUTPUT VOLTAGE RANGE							
Output Voltage Range		Programmable with TV_LDO[6:0] in 12.5mV steps		1.3500		2.9375	V
Output DAC Bits					7		bits
Output DAC LSB Size					12.5		mV
STATIC CHARACTERISTICS							
Initial Output Voltage Accuracy		$I_{LDO} = 75mA$, $T_A = +25^\circ C$		-2.5		+2.5	%
Output Voltage Accuracy		V_{LDO} programmed from 1.35V to 2.9375V, $V_{IN_LDO} = 1.8V$ to 5.5V, LDO not in dropout, $I_{LDO} = 0mA$ to 150mA, $T_A = -5^\circ C$ to $+85^\circ C$		-3		+3	%
Output Noise		f = 10Hz to 100kHz, $I_{OUT} = 15mA$, $V_{SYS} = 3.7V$, $V_{IN_LDO} = 2.05V$, $V_{LDO} = 1.85V$	Main bias circuits are in normal-power mode (SBIA_LPM = 0)		550		μV_{RMS}
			Main bias circuits are in low-power mode (SBIA_LPM = 1)		800		

Electrical Characteristics—LDO (continued)

($V_{SYS} = 3.7V$, $V_{IN_LDO} = 2.05V$, $V_{LDO} = 1.85V$, $C_{LDO} = 10\mu F$, limits are 100% production tested at $T_A = +25^\circ C$, limits over the operating temperature range ($T_A = -40^\circ C$ to $+85^\circ C$) are guaranteed by design and characterization, unless otherwise noted.)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
TIMING CHARACTERISTICS						
Enable Delay		$T_A = +25^\circ C$		0.6	1.25	ms
Soft-Start Slew Rate	dV/dt_{SS}	V_{LDO} from 10% to 90% of final value. $T_A = +25^\circ C$	0.5	1.25	2.50	mV/ μs
POWER STAGE CHARACTERISTICS						
Dropout Voltage	V_{LDO_DO}	$V_{SYS} = 3.7V$, 1.85V programmed output voltage (TV_LDO[6:0] = 0x20), $V_{IN_LDO} = 1.8V$, $I_{LDO} = 150mA$ (Note 5)		90	180	mV
Active-Discharge Impedance	R_{AD_LDO}	Regulator disabled, active discharge enabled (ADE_LDO = 1)	50	100	200	Ω
Disabled Output Leakage Current		Regulator disabled, active discharge disabled (ADE_LDO = 0), $V_{SYS} = V_{IN_LDO} = 5.5V$, $V_{LDO} = 5.5V$ and 0V	$T_A = +25^\circ C$ (Note 7)	+0.1	+1.0	μA
			$T_A = +85^\circ C$	+1.0		
Dropout On-Resistance	R_{DSON}	$V_{SYS} = 3.7V$, 1.85V programmed output voltage (TV_LDO[6:0] = 0x20), $V_{IN_LDO} = 1.8V$, $I_{LDO} = I_{MAX}$, (Note 5)	$T_A = +25^\circ C$	0.6	0.9	Ω
			$T_A = +85^\circ C$		1.2	

Note 5: Dropout is the condition where the input voltage is in its valid input range but the output cannot be properly regulated because the input voltage is not sufficiently higher than the output voltage. The dropout voltage is the difference between the input voltage and the output voltage when the regulator is in dropout. The dropout on-resistance is the resistance of the power MOSFET between the input and the output when the regulator is in dropout. Generally speaking, applications should avoid dropout by having sufficient input voltage. A dropout detection interrupt is available (DOD_R; see the [Programmer's Guide](#) for more information). For example, applications with the output voltage target of 1.85V and the maximum load current is 80mA (ILDO_MAX), has a dropout voltage of 96mV ($V_{LDO_DO} = I_{LDO_MAX} \times R_{DSON_LDO} = 80mA \times 1.2\Omega = 96mV$). To avoid dropout, the input voltage should be 1.95V ($V_{IN_LDO} = V_{LDO} + V_{LDO_DO}$).

Note 6: Guaranteed by design and characterization but not directly production tested. Production test coverage is provided by the shutdown supply current and quiescent supply current specification in the [Electrical Characteristics—Top Level](#) table.

Note 7: Guaranteed by design and characterization but not directly production tested. The ability to disconnect the active discharge resistance is functionally checked in a production test.

Electrical Characteristics—Current Sinks

($V_{SYS} = 3.7V$, limits are 100% production tested at $T_A = +25^\circ C$, limits over the operating temperature range ($T_A = -40^\circ C$ to $+85^\circ C$) are guaranteed by design and characterization, unless otherwise noted.)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
GENERAL CHARACTERISTICS						
Current Sink Quiescent Current	I_Q	Change in supply current at SYS when one channel is enabled and delivering 12.8mA, $V_{LEDx} = 0.2V$		6	12	μA
Current Sink Leakage		All current sink drivers combined, outputs disabled, $V_{LEDx} = 5.5V$	$T_A = +25^\circ C$	+0.1	+1.0	μA
			$T_A = +85^\circ C$	+1.0		
3.2mA CURRENT SINK RANGE (LED_FSx[1:0] = 0b01, VLEDx = 0.2V)						
Minimum Sink Current		BRT_LEDx[4:0] = 0b00000		0.1		mA
Maximum Sink Current		BRT_LEDx[4:0] = 0b11111		3.2		mA
Current Sink DAC Bits				5		bits
Current Sink DAC LSB				0.1		mA
Current Sink Accuracy		$T_A = +25^\circ C$	3.10	3.20	3.25	mA
		$T_A = -40^\circ C$ to $+85^\circ C$	3.03	3.20	3.36	
Dropout Voltage	V_{DO}	BRT_LEDx[4:0] = 0b11111, $I_{LEDx} = 2.9mA$		35	70	mV
6.4mA CURRENT SINK RANGE (LED_FSx[1:0] = 0b10, VLEDx = 0.2V)						
Minimum Sink Current		BRT_LEDx[4:0] = 0b00000		0.2		mA
Maximum Sink Current		BRT_LEDx[4:0] = 0b11111		6.4		mA
Current Sink DAC Bits				5		bits
Current Sink DAC LSB				0.2		mA
Current Sink Accuracy		$T_A = +25^\circ C$	6.30	6.40	6.50	mA
		$T_A = -40^\circ C$ to $+85^\circ C$	6.06	6.40	6.72	
Dropout Voltage	V_{DO}	LED_FSx[1:0] = 0b11, BRT_LEDx[4:0] = 0b11111, $I_{LEDx} = 5.75mA$		35	70	mV
12.8mA CURRENT SINK RANGE (LED_FSx[1:0] = 0b11, VLEDx = 0.2V)						
Minimum Sink Current		BRT_LEDx[4:0] = 0b00000		0.4		mA
Maximum Sink Current		BRT_LEDx[4:0] = 0b11111		12.8		mA
Current Sink DAC Bits				5		bits
Current Sink DAC LSB				0.4		mA
Current Sink Accuracy		$T_A = +25^\circ C$	12.6	12.8	13.0	mA
		$T_A = -40^\circ C$ to $+85^\circ C$	12.16	12.80	13.44	
Dropout Voltage	V_{DO}	BRT_LEDx[4:0] = 0b11111, $I_{LEDx} = 11.5mA$		35	70	mV
TIMING CHARACTERISTICS						
Root Clock Frequency			25.6	32.0	38.4	Hz

Electrical Characteristics—Current Sinks (continued)

($V_{SYS} = 3.7V$, limits are 100% production tested at $T_A = +25^\circ C$, limits over the operating temperature range ($T_A = -40^\circ C$ to $+85^\circ C$) are guaranteed by design and characterization, unless otherwise noted.)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
TIMING CHARACTERISTICS/BLINK PERIOD SETTINGS						
Minimum Blink Period			0.5		s	
			16		clocks	
Maximum Blink Period			8		s	
			256		clocks	
Blink Period LSB			0.5		s	
			16		clocks	
TIMING CHARACTERISTICS/BLINK DUTY CYCLE						
Minimum Blink Duty Cycle		D_LEDx[3:0] = 0b0000	6.25		%	
Maximum Blink Duty Cycle		D_LEDx[3:0] = 0b1111	100		%	
Blink Duty Cycle LSB			6.25		%	

Electrical Characteristics—I²C Serial Interface

($V_{SYS} = 3.7V$, $V_{IO} = 1.8V$, limits are 100% production tested at $T_A = +25^\circ C$, limits over the operating temperature range ($T_A = -40^\circ C$ to $+85^\circ C$) are guaranteed by design and characterization, unless otherwise noted.)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
POWER SUPPLY						
V_{IO} Voltage Range	V_{IO}		1.7	1.8	3.6	V
V_{IO} Bias Current		$V_{IO} = 3.6V$, $V_{SDA} = V_{SCL} = 0V$ or $3.6V$, $T_A = +25^\circ C$	-1	0	+1	μA
		$V_{IO} = 1.7V$, $V_{SDA} = V_{SCL} = 0V$ or $1.7V$	-1	0	+1	
SDA AND SCL I/O STAGE						
SCL, SDA Input High Voltage	V_{IH}	$V_{IO} = 1.7V$ to $3.6V$	0.7 x V_{IO}			V
SCL, SDA Input Low Voltage	V_{IL}	$V_{IO} = 1.7V$ to $3.6V$			0.3 x V_{IO}	V
SCL, SDA Input Hysteresis	V_{HYS}		0.05 x V_{IO}			V
SCL, SDA Input Leakage Current	I_I	$V_{IO} = 3.6V$, $V_{SCL} = V_{SDA} = 0V$ and $3.6V$	-10		+10	μA
SDA Output Low Voltage	V_{OL}	Sinking 20mA			0.4	V
SCL, SDA Pin Capacitance	C_I		10			pF
Output Fall Time from V_{IH} to V_{IL} (Note 2)	t_{OF}				120	ns

Electrical Characteristics—I²C (continued)

(V_{SYS} = 3.7V, V_{IO} = 1.8V, limits are 100% production tested at T_A = +25°C, limits over the operating temperature range (T_A = -40°C to +85°C) are guaranteed by design and characterization, unless otherwise noted.)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
I²C-COMPATIBLE INTERFACE TIMING (STANDARD, FAST AND FAST MODE PLUS) (Note 8)						
Clock Frequency	f _{SCL}		0		1000	kHz
Hold Time (REPEATED) START Condition	t _{HD;STA}		0.26			μs
SCL Low Period	t _{LOW}		0.5			μs
SCL High Period	t _{HIGH}		0.26			μs
Setup Time REPEATED START Condition	t _{SU_STA}		0.26			μs
Data Hold Time	t _{HD_DAT}		0			μs
Data Setup Time	t _{SU_DAT}		50			ns
Setup Time for STOP Condition	t _{SU_STO}		0.26			μs
Bus Free Time between STOP and START Condition	t _{BUF}		0.5			μs
Pulse Width of Suppressed Spikes	t _{SP}	Maximum pulse width of spikes that must be suppressed by the input filter		50		ns
I²C-COMPATIBLE INTERFACE TIMING (HIGH-SPEED MODE, C_B = 100pF) (Note 8)						
Clock Frequency	f _{SCL}				3.4	MHz
Setup Time REPEATED START Condition	t _{SU_STA}		160			ns
Hold Time (REPEATED) START Condition	t _{HD_STA}		160			ns
SCL Low Period	t _{LOW}		160			ns
SCL High Period	t _{HIGH}		60			ns
Data Setup Time	t _{SU_DAT}		10			ns
Data Hold Time	t _{HD_DAT}		0		70	ns
SCL Rise Time	t _{rCL}	T _A = +25°C	10		40	ns
Rise Time of SCL Signal after REPEATED START Condition and after Acknowledge Bit	t _{rCL1}	T _A = +25°C	10		80	ns
SCL Fall Time	t _{fCL}	T _A = +25°C	10		40	ns
SDA Rise Time	t _{rDA}	T _A = +25°C	10		80	ns
SDA Fall Time	t _{fDA}	T _A = +25°C	10		80	ns
Setup Time for STOP Condition	t _{SU_STO}		160			ns
Bus Capacitance	C _B				100	pF
Pulse Width of Suppressed Spikes	t _{SP}	Maximum pulse width of spikes that must be suppressed by the input filter		10		ns

Electrical Characteristics—I²C (continued)

(V_{SYS} = 3.7V, V_{IO} = 1.8V, limits are 100% production tested at T_A = +25°C, limits over the operating temperature range (T_A = -40°C to +85°C) are guaranteed by design and characterization, unless otherwise noted.)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
I²C-COMPATIBLE INTERFACE TIMING (HIGH-SPEED MODE, C_B = 400pF) (Note 8)						
Clock Frequency	f _{SCL}				1.7	MHz
Setup Time REPEATED START Condition	t _{SU_STA}		160			ns
Hold Time (REPEATED) START Condition	t _{HD_STA}		160			ns
SCL Low Period	t _{LOW}		320			ns
SCL High Period	t _{HIGH}		120			ns
Data Setup Time	t _{SU_DAT}		10			ns
Data Hold Time	t _{HD_DAT}		0		150	ns
SCL Rise Time	t _{RCL}	T _A = +25°C	20		80	ns
Rise Time of SCL Signal after REPEATED START Condition and after Acknowledge Bit	t _{RCL1}	T _A = +25°C	20		80	ns
SCL Fall Time	t _{FCL}	T _A = +25°C	20		80	ns
SDA Rise Time	t _{RDA}	T _A = +25°C	20		160	ns
SDA Fall Time	t _{FDA}	T _A = +25°C	20		160	ns
Setup Time for STOP Condition	t _{SU_STO}		160			ns
Bus Capacitance	C _B				400	pF
Pulse Width of Suppressed Spikes	t _{SP}	Maximum pulse width of spikes that must be suppressed by the input filter		10		ns

Note 8: Design guidance only. Not production tested.